

# 74CBTLVD3245

8-bit level-shifting bus switch with output enable

Rev. 2 — 12 October 2011

Product data sheet

## 1. General description

The 74CBTLVD3245 is an 8-pole, single-throw bus switch. The device features a single output enable input ( $\overline{OE}$ ) that controls eight switch channels. The switches are disabled when  $\overline{OE}$  is HIGH. Schmitt trigger action at control inputs makes the circuit tolerant of slower input rise and fall times. This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

- Supply voltage range from 3.0 V to 3.6 V
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-B/JESD36 (3.0 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ CDM AEC-Q100-011 revision B exceeds 1000 V
- 5  $\Omega$  switch connection between two ports
- Rail to rail switching on data I/O ports
- CMOS low power consumption
- Latch-up performance exceeds 250 mA per JESD78B Class I level A
- $I_{OFF}$  circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74CBTLVD3245DS	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP20 <sup>[1]</sup>	plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm	SOT724-1
74CBTLVD3245PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74CBTLVD3245BQ	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body $2.5 \times 4.5 \times 0.85\text{ mm}$	SOT764-1



[1] Also known as QSOP20 package

## 4. Functional diagram

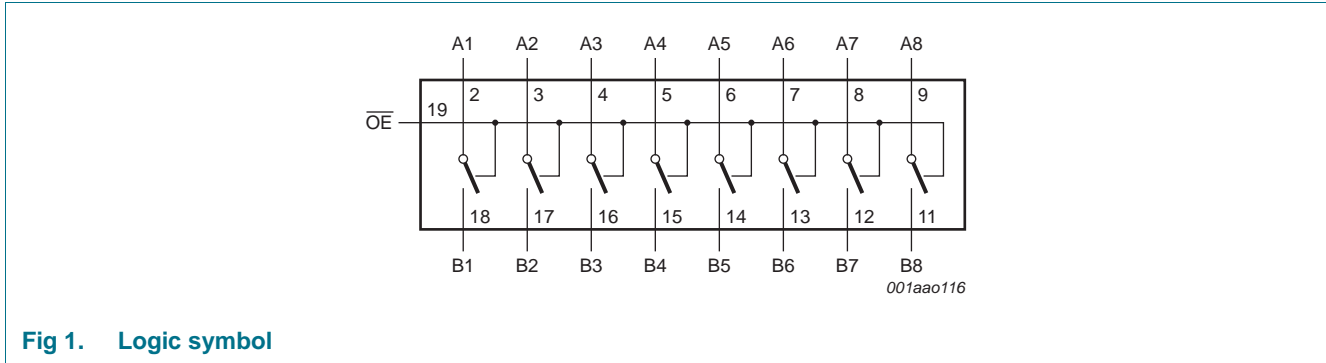


Fig 1. Logic symbol

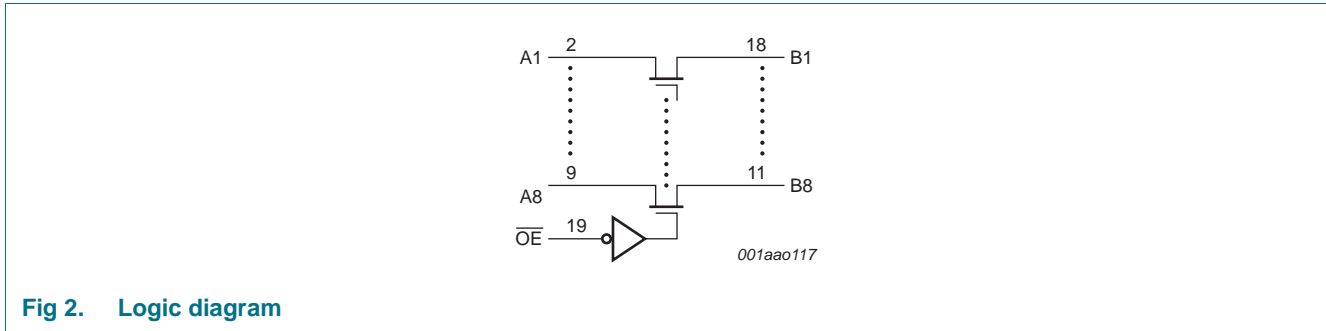


Fig 2. Logic diagram

## 5. Pinning information

### 5.1 Pinning

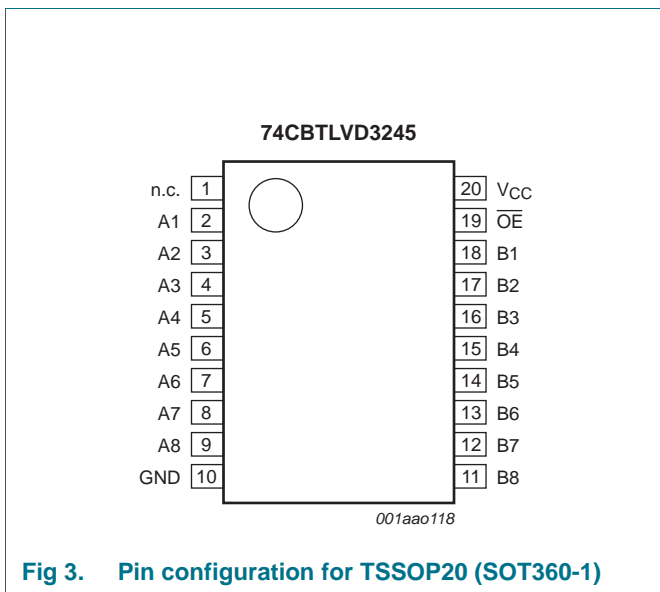


Fig 3. Pin configuration for TSSOP20 (SOT360-1)

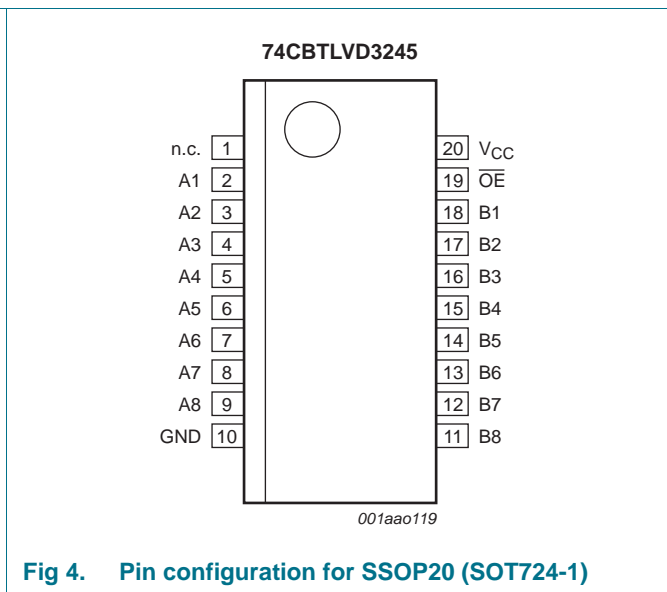
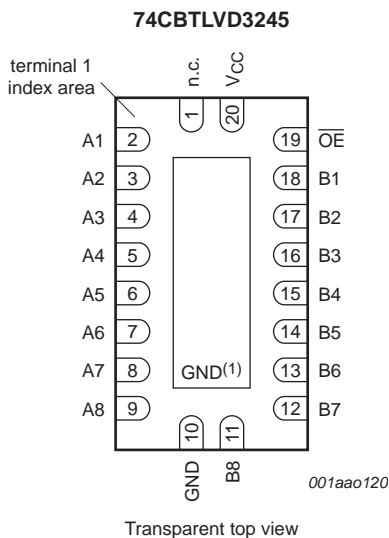


Fig 4. Pin configuration for SSOP20 (SOT724-1)



(1) This is not a supply pin, the substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad however if it is soldered the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration for DHVQFN20 (SOT764-1)

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A1 to A8	2, 3, 4, 5, 6, 7, 8, 9	data input/output (A port)
GND	10	ground (0 V)
B1 to B8	18, 17, 16, 15, 14, 13, 12, 11	data input/output (B port)
OE	19	output enable input (active LOW)
VCC	20	positive supply voltage

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

Input	Input/output
OE	An, Bn
L	An = Bn
H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
V <sub>I</sub>	input voltage		[1] -0.5	+4.6	V
V <sub>SW</sub>	switch voltage	enable and disable mode	[1] -0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	input clamping current	V <sub>IO</sub> < -0.5 V	-50	-	mA
I <sub>SK</sub>	switch clamping current	V <sub>I</sub> < -0.5 V	-50	-	mA
I <sub>SW</sub>	switch current	V <sub>SW</sub> = 0 V to V <sub>CC</sub>	-	±128	mA
I <sub>CC</sub>	supply current		-	+100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[2] -	500	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SSOP20 and TSSOP20 packages: above 60 °C the value of P<sub>tot</sub> derates linearly at 5.5 mW/K.  
For DHVQFN20 packages: above 60 °C the value of P<sub>tot</sub> derates linearly at 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		3.0	3.6	V
V <sub>I</sub>	input voltage		0	3.6	V
V <sub>SW</sub>	switch voltage	enable and disable mode	0	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 3.0 V to 3.6 V	[1] 0	200	ns/V

[1] Applies to control signal levels.

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	-	0.9	V
I <sub>I</sub>	input leakage current	pin $\overline{OE}$ ; V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.6 V	-	-	±1	-	±20	μA
V <sub>pass</sub>	pass voltage	V <sub>I</sub> = V <sub>CC</sub> ; see <a href="#">Figure 8</a> to <a href="#">Figure 12</a>	-	-	-	-	-	V

**Table 6. Static characteristics ...continued**

At recommended operating conditions voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
I <sub>S(OFF)</sub>	OFF-state leakage current	V <sub>CC</sub> = 3.6 V; see <a href="#">Figure 6</a>	-	-	±1	-	±20	μA
I <sub>S(ON)</sub>	ON-state leakage current	V <sub>CC</sub> = 3.6 V; see <a href="#">Figure 7</a>	-	-	±1	-	±20	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±10	-	±50	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.6 V; V <sub>SW</sub> = GND or V <sub>CC</sub>	-	-	20	-	50	μA
		V <sub>I</sub> = GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.6 V; V <sub>SW</sub> = GND or V <sub>CC</sub>	-	-	100	-	150	μA
ΔI <sub>CC</sub>	additional supply current	pin $\overline{OE}$ ; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 3.6 V	[2]	-	300	-	2000	μA
C <sub>I</sub>	input capacitance	pin $\overline{OE}$ ; V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	0.9	-	-	-	pF
C <sub>S(OFF)</sub>	OFF-state capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	2.5	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	9.0	-	-	-	pF

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.

[2] One input at 3 V, other inputs at V<sub>CC</sub> or GND.

### 9.1 Test circuits

V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = GND or V<sub>CC</sub>.

**Fig 6. Test circuit for measuring OFF-state leakage current (one switch)**

V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = open circuit.

**Fig 7. Test circuit for measuring ON-state leakage current (one switch)**

9.2 Typical pass voltage graphs

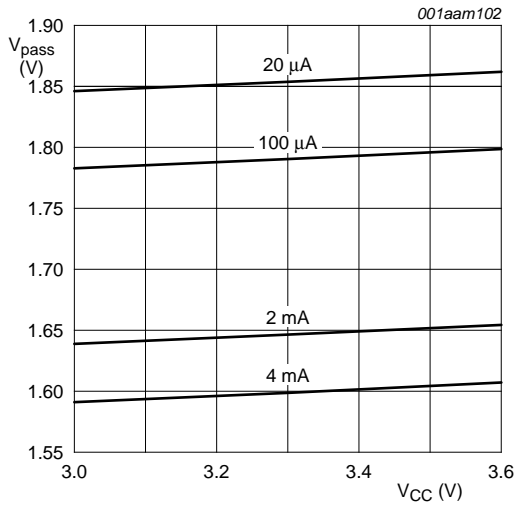


Fig 8. Pass voltage versus supply voltage; T<sub>amb</sub> = 125 °C (typical)

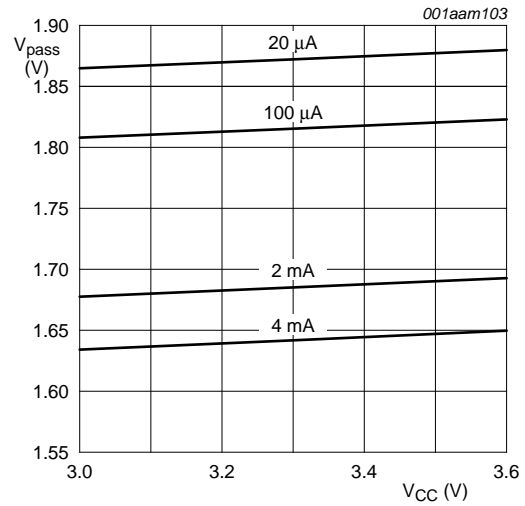


Fig 9. Pass voltage versus supply voltage; T<sub>amb</sub> = 85 °C (typical)

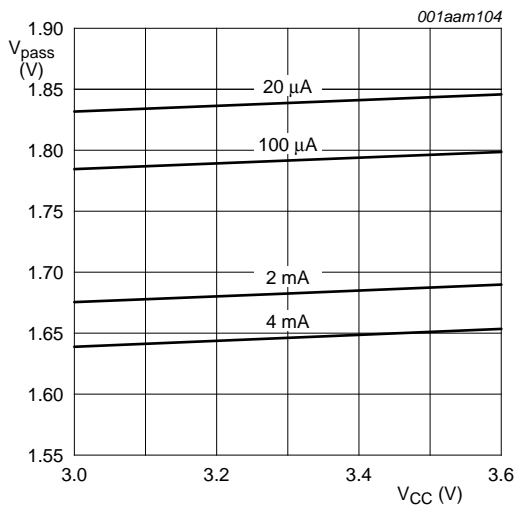


Fig 10. Pass voltage versus supply voltage; T<sub>amb</sub> = 25 °C (typical)

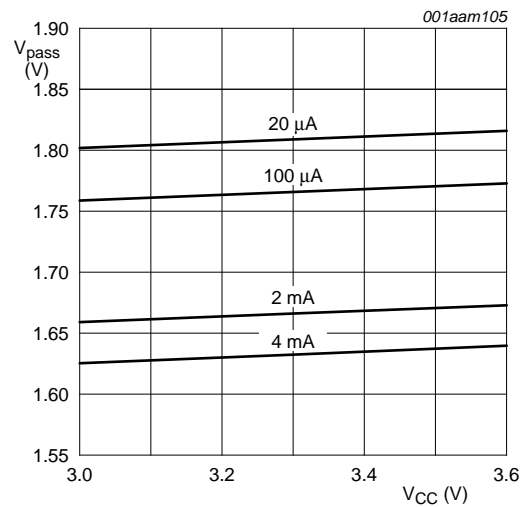


Fig 11. Pass voltage versus supply voltage; T<sub>amb</sub> = 0 °C (typical)

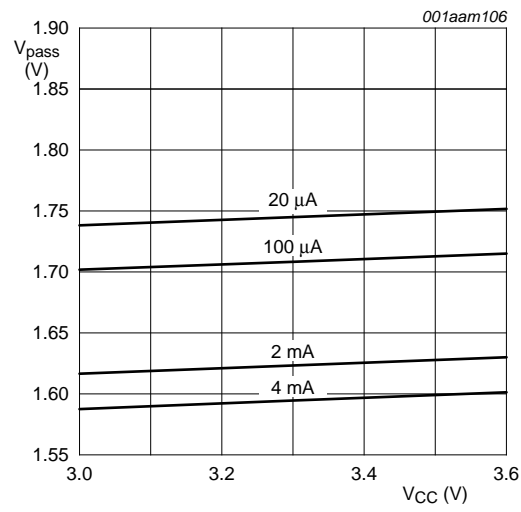


Fig 12. Pass voltage versus supply voltage; T<sub>amb</sub> = -40 °C (typical)

9.3 ON resistance

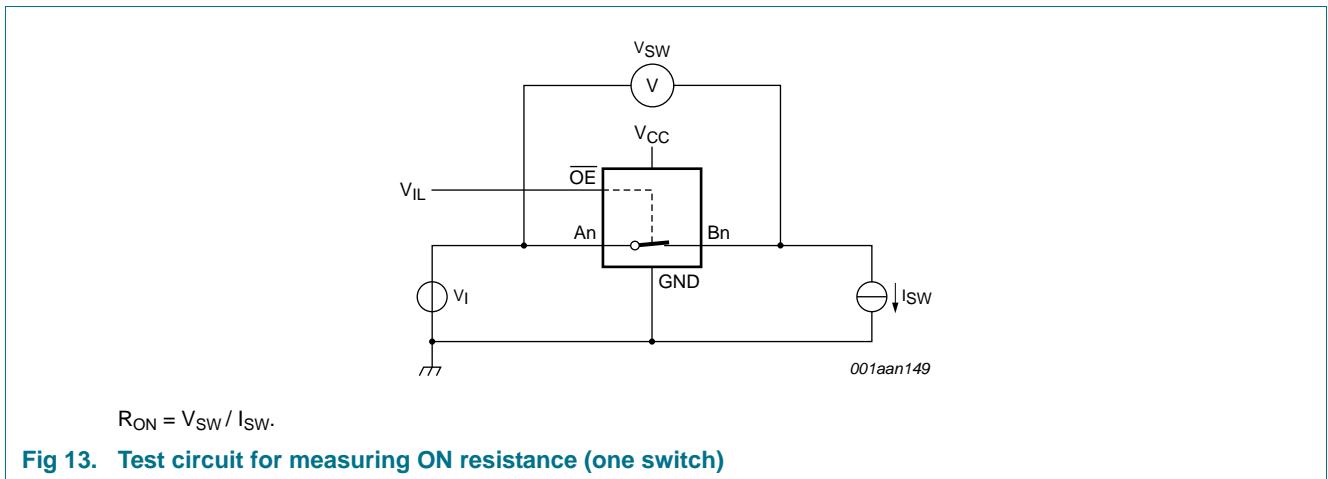
Table 7. Resistance  $R_{ON}$

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for test circuit see Figure 13.

Symbol	Parameter	Conditions	$T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to }+125\text{ }^{\circ}\text{C}$		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$R_{ON}$	ON resistance	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ <sup>[2]</sup>						
		$I_{SW} = 64\text{ mA}; V_I = 0\text{ V}$	-	3.7	7.0	-	10.0	$\Omega$
		$I_{SW} = 24\text{ mA}; V_I = 0\text{ V}$	-	3.7	7.0	-	10.0	$\Omega$
		$I_{SW} = 15\text{ mA}; V_I = 1.2\text{ V}$	-	4.7	10.0	-	12.0	$\Omega$

- [1] Typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$  and nominal  $V_{CC}$ .
- [2] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

9.4 ON resistance test circuit





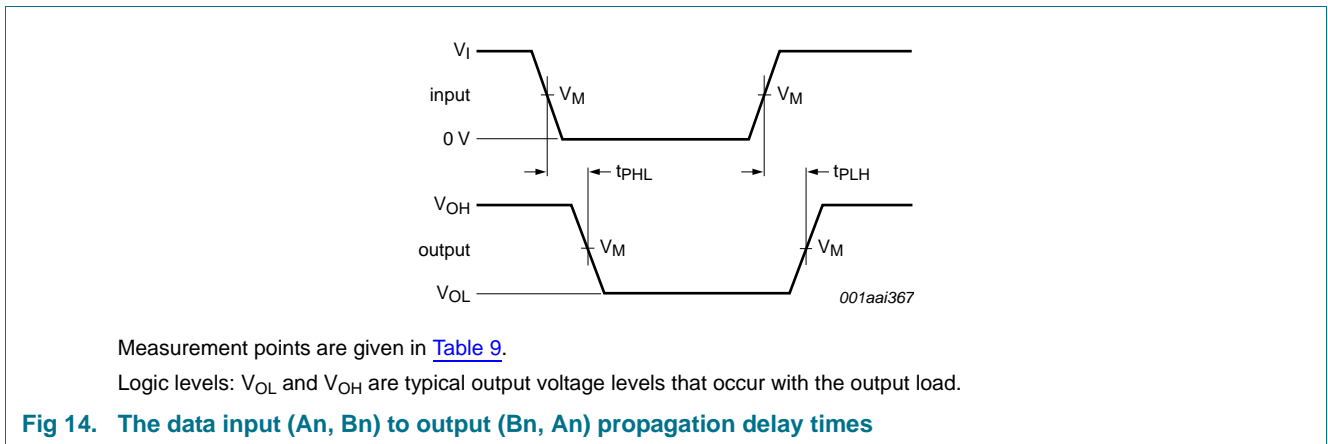
## 10. Dynamic characteristics

**Table 8. Dynamic characteristics**  
*GND = 0 V; for test circuit see Figure 16*

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	An to Bn or Bn to An; see Figure 14						
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.11	-	0.22	ns
t <sub>en</sub>	enable time	OE to An or Bn; see Figure 15						
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.5	2.9	5.0	1.5	6.0	ns
t <sub>dis</sub>	disable time	OE to An or Bn; see Figure 15						
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.8	3.4	7.0	0.8	8.0	ns

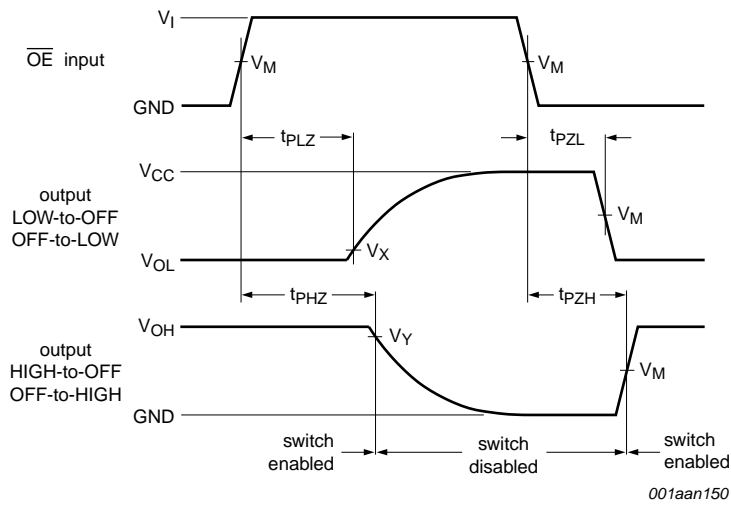
- [1] All typical values are measured at T<sub>amb</sub> = 25 °C and at nominal V<sub>CC</sub>.
- [2] The propagation delay is the calculated RC time constant of the on-state resistance of the switch and the load capacitance, when driven by an ideal voltage source (zero output impedance).
- [3] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.
- [4] t<sub>en</sub> is the same as t<sub>PZH</sub> and t<sub>PZL</sub>.
- [5] t<sub>dis</sub> is the same as t<sub>PHZ</sub> and t<sub>PLZ</sub>.

## 11. Waveforms



**Table 9. Measurement points**

Supply voltage	Input			Output		
V <sub>CC</sub>	V <sub>M</sub>	V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>	V <sub>M</sub>	V <sub>X</sub>	V <sub>Y</sub>
3.0 V to 3.6 V	0.5V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.0 ns	0.9 V	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> - 0.15 V

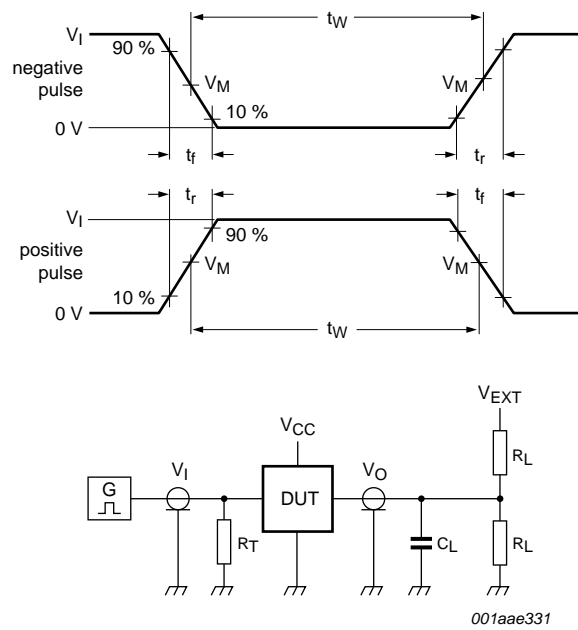


001aan150

Measurement points are given in [Table 9](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 15. Enable and disable times**



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 16. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Load		$V_{EXT}$		
$V_{CC}$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
3.0 V to 3.6 V	30 pF	1 kΩ	open	GND	3.6 V

### 11.1 Additional dynamic characteristics

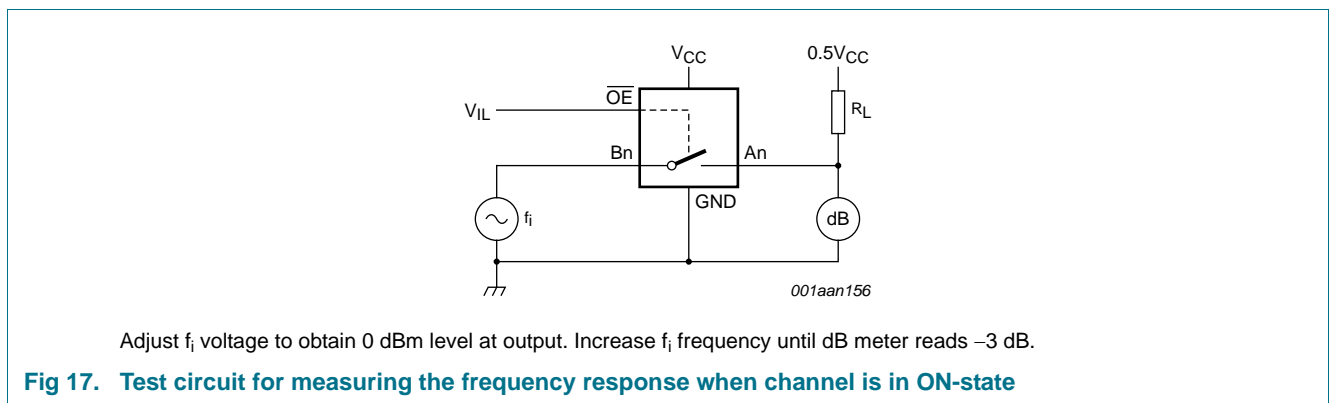
**Table 11. Additional dynamic characteristics**

$GND = 0 V$ .

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^{\circ}\text{C}$			Unit	
			Min	Typ	Max		
$f_{(-3dB)}$	-3 dB frequency response	$V_{CC} = 3.3\text{ V}$ ; $R_L = 50\text{ }\Omega$ ; see <a href="#">Figure 17</a>	[1]	-	575	-	MHz

[1]  $f_i$  is biased at  $0.5V_{CC}$ .

### 11.2 Test circuit



12. Package outline

SSOP20: plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm SOT724-1

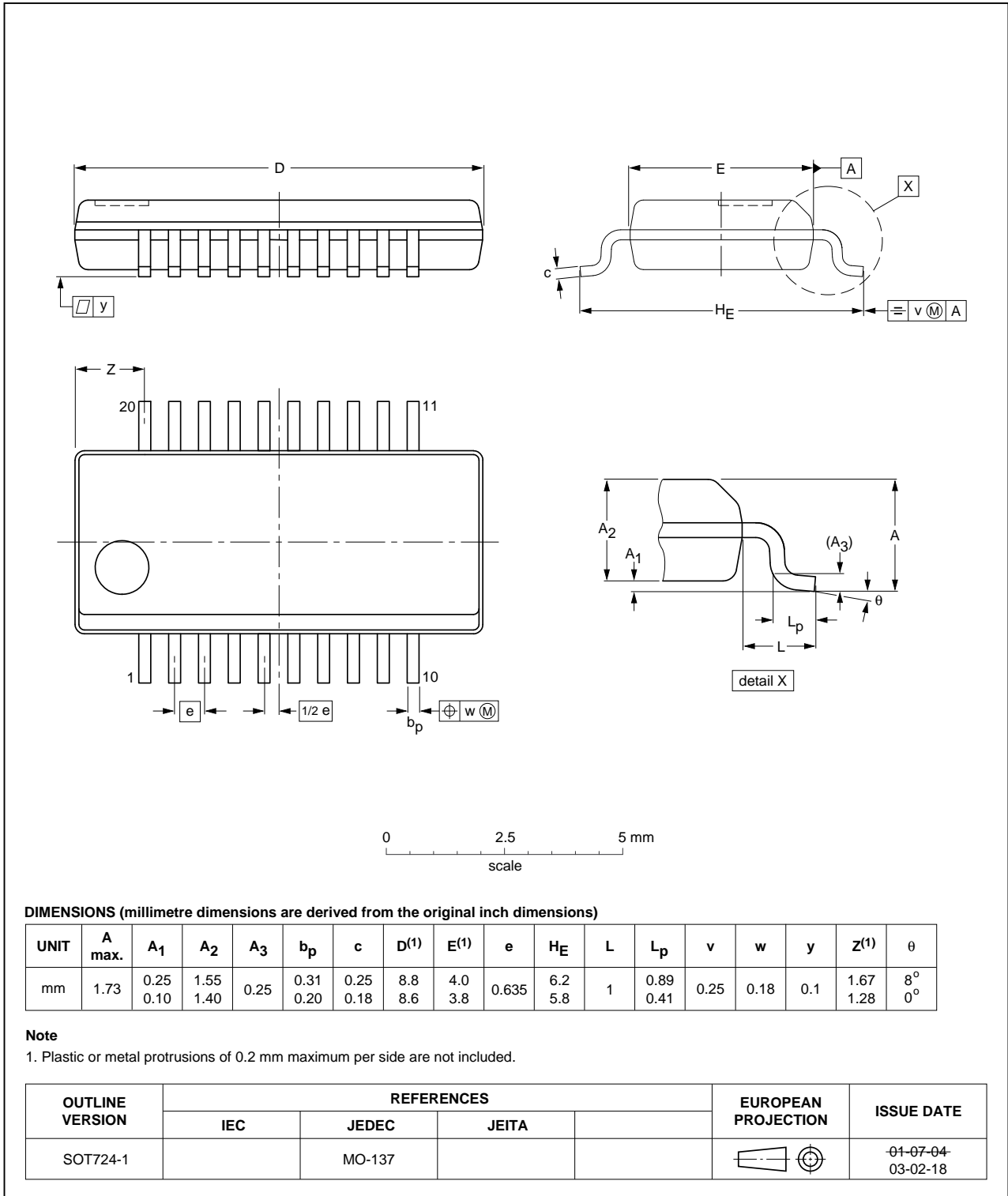


Fig 18. Package outline SOT724-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



Fig 19. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

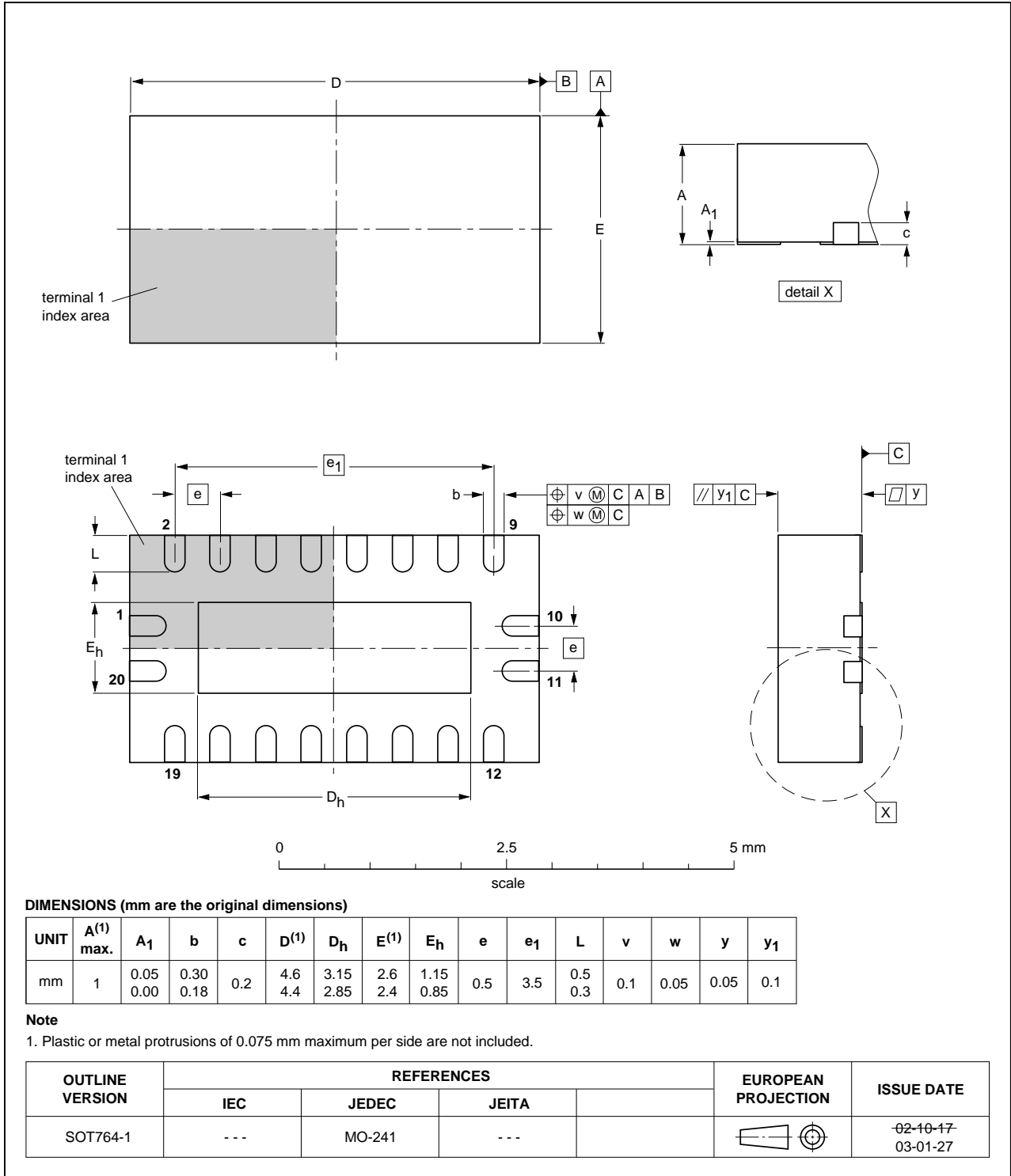


Fig 20. Package outline SOT764-1 (DHVQFN20)

## 13. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74CBTLVD3245 v.2	20111012	Product data sheet	-	74CBTLVD3245 v.1
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Section 2 "Features and benefits"</a> MM JESD22-A115-A exceeds 200 V removed.</li> </ul>			
74CBTLVD3245 v.1	20110506	Product data sheet	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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**17. Contents**

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